

ABSTRACT

DIE BONDING APPARATUS COMPRISING AN INERT GAS ENVIRONMENT

5 A die bonding apparatus comprising a first inert gas container having a first inert gas concentration, and a second inert gas container having a second inert gas concentration enclosed within the first inert gas container. The second inert gas concentration is higher than the first inert gas concentration. The die bonding apparatus further comprises a bond head located in the second inert gas container for receiving a die for bonding, and
10 a third inert gas container having an inert gas environment that is separate from the first and second inert gas containers and where a substrate is locatable for die bonding. The bond head is operative to move the die between a first position within the second inert container and a second position within the third inert gas container to bond the die onto the substrate located in the third inert gas container.

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[FIG. 1]